

What is claimed is:

1. An imaging apparatus comprising:

an imaging portion in which a cover glass is adhered to an imaging surface side of a solid-state image pickup device as if sandwiching leads, a slight air gap is formed between the cover glass and the imaging surface of the solid-state image pickup device and a circumference of the cover glass is larger than the solid-state image pickup device, and

a circuit board having an accommodation concave portion for accommodating the solid-state image pickup device so as to connect the leads to terminals on an upper edge of the accommodation concave portion,

wherein the circumference of the cover glass adheres to the circuit board in a state of sealing the accommodation concave portion.

2. The imaging apparatus according to claim 1,

wherein a projection projecting to the outside from a clearance of a part of the lead arrangement is provided on the circumference on the leads-placed side of the cover glass so as to adhere the periphery of the cover glass including the projection to the upper edge of the accommodation concave portion of the circuit board.

3. The imaging apparatus according to claim 1,

wherein levels are provided on the circumference of the accommodation concave portion of the circuit board, and another cover glass is placed on an upside of the cover glass by utilizing the levels.

4. An imaging apparatus comprising:

an imaging portion in which a cover glass is adhered to an imaging surface side of a solid-state image pickup device as if sandwiching leads,

a slight air gap is formed between the cover glass and an imaging surface of the solid-state image pickup device and a circumference of the cover glass is larger than the solid-state image pickup device, and

a circuit board having an accommodation concave portion for accommodating the solid-state image pickup device so as to connect the leads to terminals on an upper edge of the accommodation concave portion,

wherein the circumference on the leads-placed side of the cover glass projects further than the leads and an insulative elastic member places between the cover glass and the leads so as to adhere the circumference of the cover glass to the circuit board and seal the accommodation concave portion while maintaining good electrical contact between the leads

and the terminals on the circuit board side with the insulative elastic member.

5. The imaging apparatus according to claim 4,

wherein levels are provided on the circumference of the accommodation concave portion of the circuit board, and another cover glass is placed on an upside of the cover glass by utilizing the levels.